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PATENT

Docket No. P1410

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

SERGEY LOPATIN

ALEXANDER H. NICKEL

PAUL L. KING

SERIAL NO.:

10/084,563

**EXAMINER: UNASSIGNED** 

FILED:

JUN 1 4 2002

FEBRUARY 26, 2002

ART UNIT 2812

FOR:

METHOD OF REDUCING ELECTROMIGRATION IN A COPPER LINE BY ELECTROPLATING AN INTERIM COPPER-ZINC ALLOY THIN FILM ON A COPPER SURFACE AND A

SEMICONDUCTOR DEVICE THEREBY FORMED

## COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

## TRANSMITTAL LETTER

Dear Sir:

In connection with the above referenced patent application, transmitted here with are the following:

- 1. Information Disclosure Statement (1 pages);
- 2. Information Disclosure Statement By Applicant Form PTO-1449 (1 page);
- 3. U.S. Patent No. 6,197,181 B1 (18 pages);
- 4. U.S. Patent No. 6,022,808 (6 pages);
- 5. Article "A Practical Guide to Semiconductor Processing" (3 pages);
- 6. Article "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization" (2 pages);
- 7. Article "Using Electrochemistry to Improve Copper Interconnect" (4 pages);
- 8. Article "ECD Seed Layer for Inlaid Copper Metallization" (2 pages); and

9. Post card in acknowledgment of-receipt of all transmitted materials.

Please date-stamp the enclosed postcard and return same to the undersigned in acknowledgment of receipt of all transmitted material.

Respectfully submitted,

Victor Flores

Reg. No. 29,638

VF/sgs June 14, 2002 LARIVIERE, GRUBMAN & PAYNE, LLP P.O. Box 3140 Monterey, CA 93942 (831) 649-8800